

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	7619085	(carrier substrate) with (bury buried within) (conductor conductive metal cu copper interconnect\$ metallic metallization)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/22 11:12
L2	45906	(carrier substrate) with (bury buried within) with (conductor conductive metal cu copper interconnect\$ metallic metallization)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/22 11:12
L3	10562	semiconductor with 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/22 11:13
L4	69	(rightangle right) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/22 11:13